



AEROSPACE MATERIAL SPECIFICATIONS

SOCIETY OF AUTOMOTIVE ENGINEERS, Inc.

485 Lexington Ave., New York, N. Y. 10017

AMS 2408B

Superseding AMS 2408A

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TIN PLATING

1. ACKNOWLEDGMENT: A vendor shall mention this specification number and its revision letter in all quotations and when acknowledging purchase orders.
2. APPLICATION: Primarily to provide a surface for soldering, to prevent galling or seizing of metal surfaces, or to prevent the formation of case during nitriding. Corrosion resistance is improved by tin plating.
3. PREPARATION:
 - 3.1 Before placing parts in plating solutions, they shall have chemically clean surfaces, prepared with minimum abrasion, erosion, or pitting.
 - 3.2 Parts having hardness higher than Rockwell C 45 and which have been ground after heat treatment should be suitably stress-relieved before cleaning for plating. Temperatures to which parts are heated shall be such that maximum stress-relief is obtained without reducing hardness of parts below drawing limits.
4. PROCEDURE:
 - 4.1 Unless otherwise permitted by purchaser, tin shall be electrodeposited directly on the basis metal from an alkaline stannate solution, a stannous sulphate solution, or a stannous fluoborate solution.
 - 4.2 Unless otherwise specified, after plating, washing, and drying, all parts having hardness higher than Rockwell C 45 shall be suitably heated to relieve possible embrittlement. Temperatures to which parts are heated shall in no case be so high as to reduce hardness of the basis metal below drawing limits but shall be not lower than 300 F (149 C) for not less than 1 hr, unless otherwise specified. At higher temperatures, the time may be shortened.
5. THICKNESS:
 - 5.1 Plate thickness may be specified by this specification number and a suffix number designating the minimum thickness in ten-thousandths of an inch; thus AMS 2408-1 designates a thickness of 0.0001 - 0.0003 in. AMS 2408-6 designates a thickness of 0.0006 - 0.0008 in., etc. A tolerance of +0.0002 in. in thickness is allowed, unless otherwise specified.
 - 5.2 Where "tin flash" is specified, the thickness of tin shall be approximately 0.0001 inch.
 - 5.3 Requirements for plate thickness shall not apply to small holes or deep recesses unless so specified on drawings.
 - 5.4 Thickness of tin plate shall be determined by micrometer measurement, stripping or dropping tests, or by suitable nondestructive methods. These methods shall be calibrated by microscopic examination.

Note 1. Parts plated to provide a surface for soldering should have a tin flash.

Note 2. Parts plated to prevent galling or seizing should have a plate thickness of 0.0002 - 0.0004 inch.

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